

Press Release

Viscom implements groundbreaking 3D technology across its entire product range

Hanover, Germany, November 2018 – **Viscom AG will premier a new 3D bond inspection system at electronica 2018 in Munich. The Hanover-based inspection technology expert is thus expanding its diverse 3D product range from 3D SPI, 3D AOI and 3D X-ray technology to include bond inspection, further reinforcing its technology leadership in 3D inline inspection for the electronics manufacturing industry.**

The highlights at electronica 2018 include the latest innovation by Viscom AG: the new 3D bond system, type S6056BO with state-of-the-art camera technology (XM and XMplus). The new system meets the increased requirements placed on wire bond inspection in the e-mobility sector (e.g. for storage batteries), as well as those placed on other safety-relevant high-performance electronics.

Complementary to the company's uniquely wide range of solutions, trade show visitors will be able to see the extremely high levels of quality and speed achievable in 3D AOI inspection. The successful premium system S3088 *ultra gold* features genuine solder joint measurement. It is the only system with eight angled cameras to provide precise 3D measurement analysis, enabling optimal FPY results.

The S3088 CCI (Conformal Coating Inspection) system is a further highlight. Designed for simultaneous SMD inspection and conformal coating inspection, the system meets the growing demand in the consumer electronics sector. Defects, cracks, blisters, cavities and paste smearing on the printed circuit board are reliably detected using ultraviolet light. To

optimize the process, the layer thickness can be measured at multiple points using 3D spot measurement.

In SMT manufacturing, 3D inline X-ray inspection is enjoying increasing success. The innovative, award-winning X7056-II X-ray system inspects electronic components specifically for concealed solder joints or blow holes (voids) in solder joints, or material defects — at an ultra-fast handling speed of down to four seconds. 3D reconstruction with the X7056-II is based on planar CT. For complex overlaps, which are virtually the rule with double-sided PCBs, leveraging the superb three-dimensional inspection possibilities offered by the system makes all significant features sharply visible in clear slice images to enable precise evaluations – even with shadowing caused by components or on multilayer boards.

The X8011-II PCB 3D MXI system by Viscom features universal, manual X-ray inspection. Flexible, interchangeable modules enable perfect specimen handling for prototype, random sampling and small series inspection. The Viscom Quality Uplink can be used for the offline X-ray system. By linking the inspection results from SPI, AOI, AXI and MXI, this function provides simplified classification and effective process control.

Artificial intelligence is another topic that Viscom deals with from several perspectives: for example, computer-based verification of defects already assists employees effectively in preventing pseudo-errors, thus increasing the overall process quality. Deep learning will play an increasingly important role in Viscom's program creation and component assignment, making it increasingly possible to recognize new product introduction (NPI) components fully automatically.

In line with the motto "Solutions for me.", Viscom offers customized inspection solutions with superb performance and excellent, comprehensive service with its own worldwide network of technicians and

engineers to keep systems running smoothly. Viscom is exhibiting at stand 642 in hall A3.

Caption: Viscom AG offers customized inspection solutions for the electronics industry from a single source – from 3D SPI, 3D AOI and 3D AXI/MXI to 3D bond and CCI systems.

About Viscom

Viscom AG develops, manufactures, and sells high-quality inspection systems. The portfolio encompasses the complete bandwidth of optical and X-ray inspections. In the area of assembly inspection for electronics manufacturing, the company is among the leading suppliers worldwide. Viscom systems can be configured specifically for each customer and can be interlinked. The company headquarters and manufacturing location is in Hanover, Germany. With a large network of branches, application centers, service support points and representatives, Viscom is represented internationally. Founded in 1984, Viscom has been listed on the Frankfurt Stock Exchange (ISIN: DE0007846867) since 2006. For additional information visit <https://www.viscom.de/>